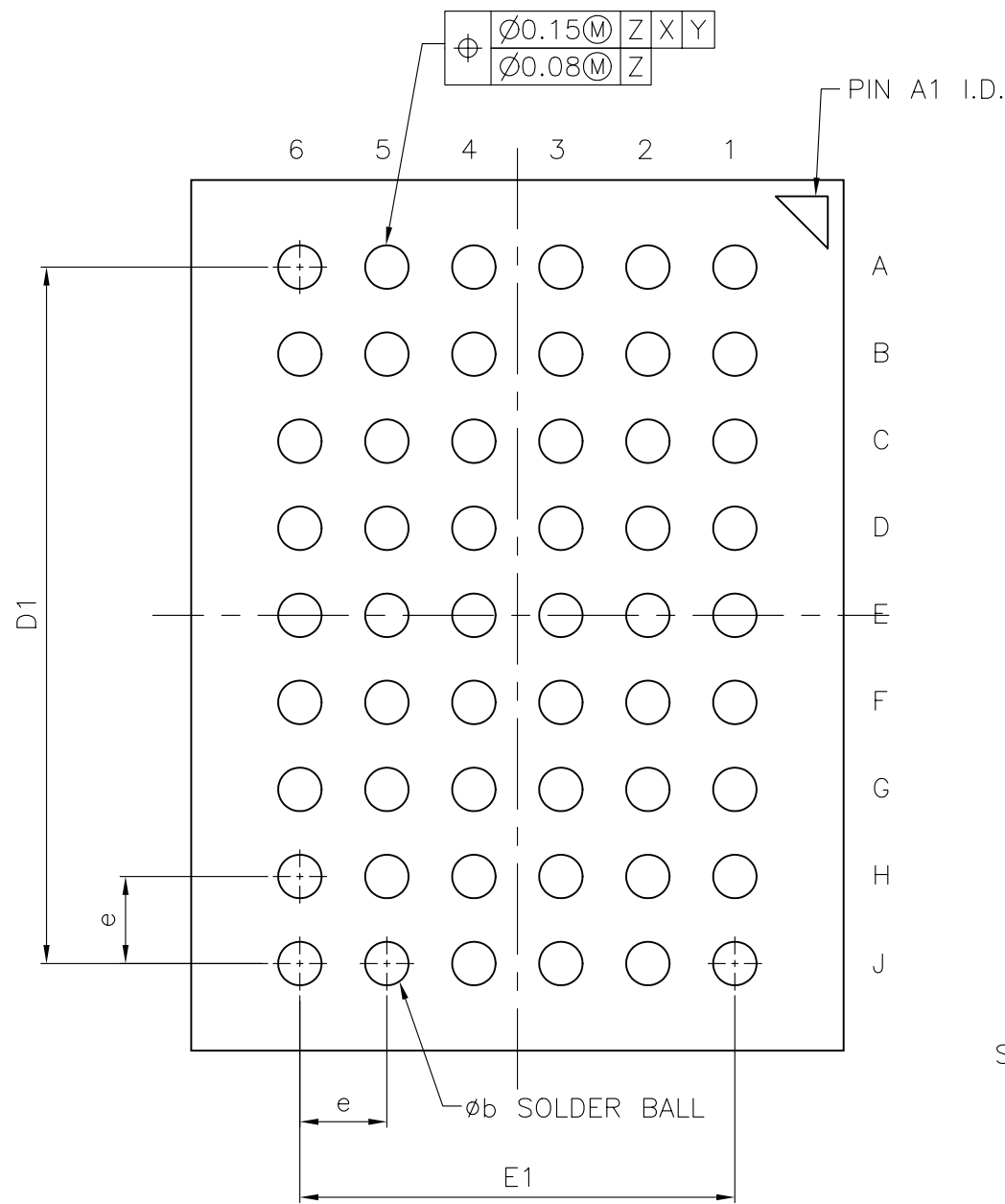
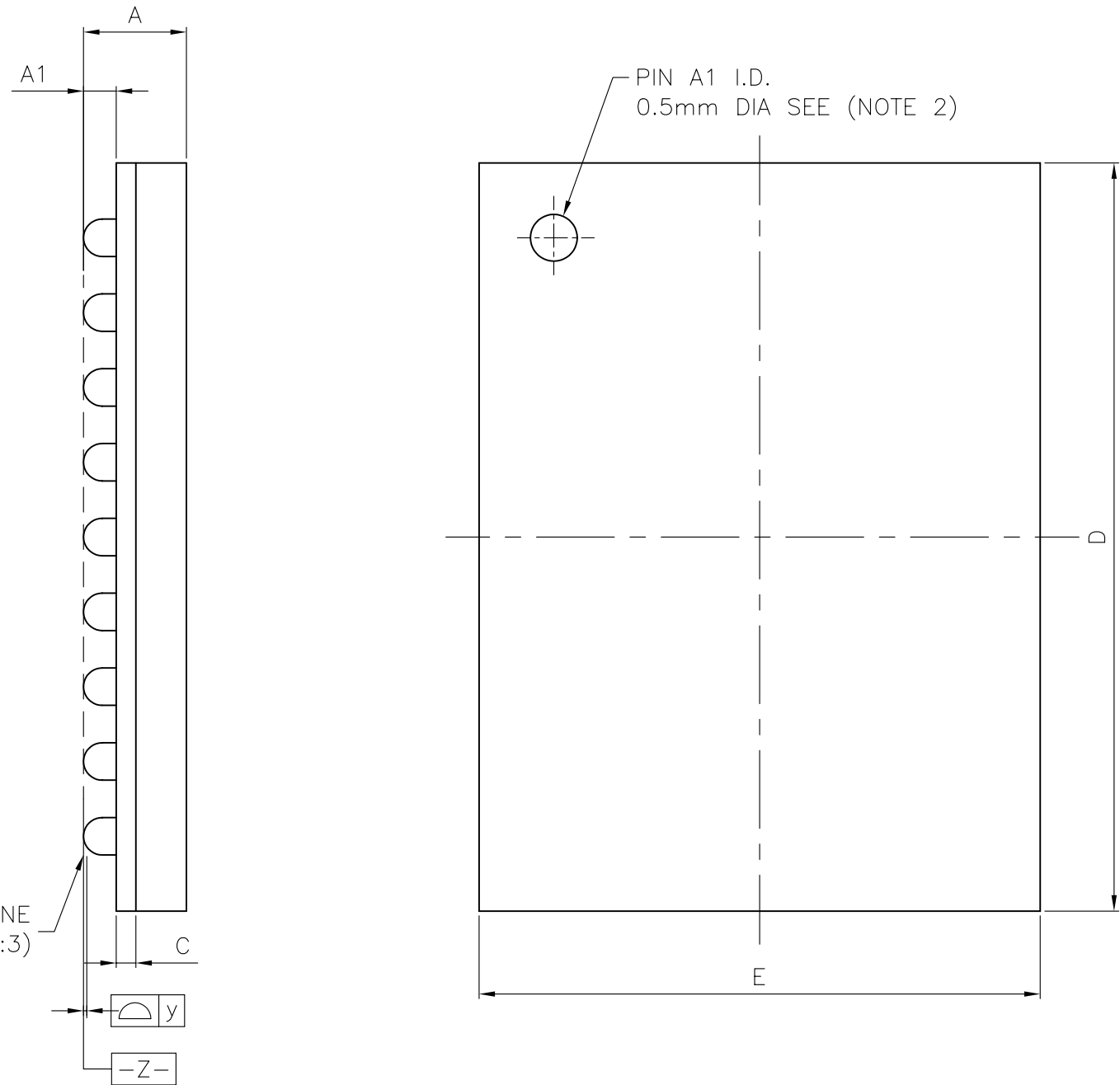


BOTTOM SIDE BOTTOM VIEW



TOP SIDE TOP VIEW



SEATING PLANE (NOTE:3)

NOTE :

1. ALL DIMENSION ARE IN MILLIMETERS.
2. PIN A1 ID. TO BE MARKED BY LASER.
3. PRIMARY DATUM $[-Z-]$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. "e" REPRESENTS THE MAXIMUM SOLDER BALL GRID PITCH.
5. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL PITCH. PARALLEL TO PRIMARY DATUM $[-Z-]$.

SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	0.90	—	1.10
A1	0.25	—	0.35
ϕb	0.35	0.40	0.45
c	—	0.21	—
D	7.90	8.00	8.10
D1	6.30	6.40	6.50
E	5.90	6.00	6.10
E1	3.90	4.00	4.10
e	—	0.80	—
y	0.00	—	0.10

CUSTOMER :

LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z
PRECISION IND., LTD. TAICHUNG., TAIWAN. R. O. C

APPROVED BY DATE

TITLE:

DRAW BY:
Sandy Sue 07/13/05

MINI BGA 54L(6x8mm) PACKAGE
OUTLINE DRAWING

CHECK BY:
S. S. Lin 07/14/05

APPROVAL:
Kevin Liao 07/14/05

DWG. NO. PO-MBGA-018 REV. 0

APPROVAL:
Jack Tu 07/14/05

UNIT : mm SCALE : 15/1 SHEET 1 OF 1